

Product Texts

LNP THERMOCOMP LC008EXP compound is based on Polyetheretherketone (PEEK) resin containing 40% carbon fiber. Added features of this grade include: Electrically Conductive, Easy Molding.

Mechanical properties	Value	Unit	Test Standard
ISO Data			
Tensile Modulus	26200	MPa	ISO 527
Stress at break	256	MPa	ISO 527
Strain at break	1.6	%	ISO 527
Flexural modulus	22900	MPa	ISO 178
Izod impact strength, +23°C, 4mm	45	kJ/m ²	ISO 180/1U
Izod notched impact strength, +23°C, 4mm	9	kJ/m ²	ISO 180/1A

Thermal properties	Value	Unit	Test Standard
ISO Data			
Temp. of deflection under load, 1.80 MPa	300	°C	ISO 75-1/-2
Coeff. of linear therm. expansion, parallel	4	E-6/K	ISO 11359-1/-2
Coeff. of linear therm. expansion, normal	41	E-6/K	ISO 11359-1/-2

Other properties	Value	Unit	Test Standard
Density	1450	kg/m ³	ISO 1183

Processing Recommendation Injection Molding	Value	Unit	Test Standard
Pre-drying - Temperature	120 - 150	°C	-
Pre-drying - Time	4	h	-
Processing humidity	≤0.1	%	-
Melt temperature	380 - 390	°C	-
Mold temperature	140 - 165	°C	-
Zone 1	350 - 360	°C	-
Zone 2	365 - 375	°C	-
Zone 3	380 - 395	°C	-
Screw speed	60 - 100	rpm	-
Back pressure	0.3 - 0.7	MPa	-

Characteristics

Processing

Injection Molding

Regional Availability

North America, Europe, Asia Pacific

Special Characteristics

Increased electrical conductivity